

# Dr. Jiajun Wu

POST-DOC FELLOW · AI CHIP CENTER FOR EMERGING SMART SYSTEMS

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## Education

### University of Hong Kong (HKU)

Hong Kong SAR

PHD CANDIDATE

2021 - 2025

- Supervisor: Dr. Hayden Kwok-Hay So
- Research Field: *Hardware Acceleration Systems for AI Applications*
- Thesis Title: *Mixed-Precision Deep Neural Networks Acceleration: Architecture-Software Co-Design Approaches*

### Huazhong University of Science and Technology (HUST)

China

BENG, INTEGRATED CIRCUIT DESIGN

2017 - 2021

- Honored Thesis & Honored Graduate
- GPA: 3.89/4.0
- Supervisor: Prof. Chao Wang

## Experience

### Huazhong University of Science and Technology - Research Assistant

Wuhan, China

ADVISORS: PROF. CHAO WANG

2019-2021

- Research Topic: Energy-Efficient brain-inspired computing

### Zhuhai UM Science & Technology Research Institute - Research Intern

Zhuhai, China

ADVISOR: PROF. SAI-WENG SIN

Jul. 2020-Oct. 2020

- Research Topic: Analog Computing in the event sensor front-end

### Singapore University of Technology and Design - Visiting Student

Singapore

ADVISOR: DR. SHAOWEI LIN

Jan. 2020-Feb. 2020

- Project: Study of neuromorphic computing in machine learning algorithms

### Wuxi EDA Institute, Peking University - Visiting Scholar

Wuxi, China

ADVISOR: PROF. YUN LIANG

Sep. 2024-Jan. 2025

- Project: Balancing prefill and decode in LLM inference based on phase-level pipeline on FPGA

## Publications

**J. Wu, M. Song, J. Zhao, Y. Gao, J. Li, and H. K. -H. So.** 2025. TATAA: Programmable Mixed-Precision Transformer Acceleration with a Transformable Arithmetic Architecture. *ACM Trans. Reconfigurable Technol. Syst. (TRET)* 18, 1, Article 14 (March 2025), 31 pages.

**J. Wu**, M. Song, J. Zhao and H. K. -H. So, “A Case for Low Bitwidth Floating Point Arithmetic on FPGA for Transformer Based DNN Inference,” 2024 IEEE International Parallel and Distributed Processing Symposium Workshops (**IPDPSW**), San Francisco, CA, USA, 2024, pp. 178-185

**J. Wu**, J. Zhou, Y. Gao, Y. Ding, N. Wong and H. K. -H. So, “MSD: Mixing Signed Digit Representations for Hardware-efficient DNN Acceleration on FPGA with Heterogeneous Resources,” 2023 IEEE 31st Annual International Symposium on Field-Programmable Custom Computing Machines (**FCCM**), Marina Del Rey, CA, USA, 2023, pp. 94-104

Y. Ding<sup>1</sup>, **J. Wu**<sup>1</sup>, Y. Gao, M. Wang and H. K. -H. So, “Model-Platform Optimized Deep Neural Network Accelerator Generation through Mixed-Integer Geometric Programming,” 2023 IEEE 31st Annual International Symposium on Field-Programmable Custom Computing Machines (**FCCM**), Marina Del Rey, CA, USA, 2023, pp. 83-93

**J. Wu**, Y. Zhan, Z. Peng, X. Ji, G. Yu, R. Zhao and C. Wang, “Efficient Design of Spiking Neural Network With STDP Learning Based on Fast CORDIC,” in IEEE Transactions on Circuits and Systems I: Regular Papers (**TCAS-I**), vol. 68, no. 6, pp. 2522-2534, June 2021

**J. Wu**, X. Huang, L. Yang, J. Wang, B. Liu, Z. Wen, J. Li, G. Yu, K. -S. Chong and C. Wang, “An Energy-Efficient Deep Belief Network Processor Based on Heterogeneous Multi-Core Architecture With Transposable Memory and On-Chip Learning,” in IEEE Journal on Emerging and Selected Topics in Circuits and Systems (**JETCAS**), vol. 11, no. 4, pp. 725-738, Dec. 2021

**J. Wu**, X. Huang, L. Yang, L. Wang, J. Wang, Z. Liu, K. -S. Chong, S. Lin and C. Wang, “An Energy-efficient Multi-core Restricted Boltzmann Machine Processor with On-chip Bio-plausible Learning and Reconfigurable Sparsity,” 2020 IEEE Asian Solid-State Circuits Conference (**A-SSCC**), Hiroshima, Japan, 2020, pp. 1-4

J. Zhou<sup>2</sup>, **J. Wu**<sup>2</sup>, Y. Gao, Y. Ding, C. Tao, B. Li, F. Tu, K. -T. Cheng, H. K. -H. So, and N. Wong, “DyBit: Dynamic Bit-Precision Numbers for Efficient Quantized Neural Network Inference,” in IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**), Early Access

M. Song, **J. Wu**, Y. Ding and H. K. -H. So, “SqueezeBlock: A Transparent Weight Compression Scheme for Deep Neural Networks,” 2023 International Conference on Field Programmable Technology (**ICFPT**), Yokohama, Japan, 2023, pp. 238-243

J. Xu, Y. Zhan, Y. Li, **J. Wu**, X. Ji, G. Yu, W. Jiang, R. Zhao and C. Wang, “In situ aging-aware error monitoring scheme for IMPLY-based memristive computing-in-memory systems,” IEEE Transactions on Circuits and Systems I: Regular Papers (**TCAS-I**), 69(1), pp.309-321

B. Liu, Z. Wen, H. Zhu, J. Lai, **J. Wu**, H. Ping, W. Liu, G. Yu, J. Zhang, Z. Liu, H. Zeng and C. Wang “Energy-efficient intelligent pulmonary auscultation for post COVID-19 era wearable monitoring enabled by two-stage hybrid neural network,” in 2022 IEEE International Symposium on Circuits and Systems (**ISCAS**), pp. 2220-2224. IEEE, 2022

Q. Wang, Y. Zhan, B. Liu, **J. Wu**, Y. Shi, G. Yu, and C. Wang. “A Reconfigurable Area and Energy Efficient Hardware Accelerator of Five High-order Operators for Vision Sensor Based Robot Systems,” in 2021 IEEE International Conference on Integrated Circuits, Technologies and Applications (**ICTA**), pp. 189-190. IEEE, 2021

## Selected Awards

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2021 **Postgraduate Research Scholarship**, University of Hong Kong

2021 **Honored Thesis & Honored Graduate**, Huazhong University of Science and Technology

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<sup>1</sup>Equal Contribution

<sup>2</sup>Equal Contribution

- 2019 **Second Prize in Challenge Cup College Students' Extracurricular Academic Science and Technology Works Contest**, Ministry of Education, P. R. China
- 2019 **Second Prize in China University Intelligent Robot Creative Competition**, China Association for Science and Technology
- 2019 **Third Prize in TI Cup College Students' Electronic Design Competition**, Texas Instruments, and Ministry of Education, P. R. China
- 2019 **Merit Student (5% ~ 10%)**, Huazhong University of Science and Technology
- 2018 **First Prize in TI Cup Hubei Province College Students' Electronic Design Competition (TI 杯全国大学生电子设计竞赛一等奖)**, Texas Instruments, and Ministry of Education, P. R. China

## Academic Presentations

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November 2024. *The Case for Mixed Integer and Floating-point Acceleration of Transformer Models*. In ACCESS Seminar, AI Chip Center for Emerging Smart Systems (ACCESS), Hong Kong

May 2023. *MSD: Mixing Signed Digit Representations for Hardware-efficient DNN Acceleration on FPGA with Heterogeneous Resources*. In 2023 IEEE 31st Annual International Symposium on Field-Programmable Custom Computing Machines (FCCM), CA, USA

August 2021. *Energy-efficient DNN Hardware Accelerator with On-chip Learning –A Deep Belief Network Processor Case*. Invited by IEEE CASS-EDS-SSCS HUST Student Branch Chapter, Wuhan, China.

October 2020. *An Energy-efficient Multi-core Restricted Boltzmann Machine Processor with On-chip Bio-plausible Learning and Reconfigurable Sparsity*. In 2020 IEEE Asian Solid-State Circuits Conference (A-SSCC), Virtual Event.

## Teaching Experience

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2025	<b>ELEC6098, Electronic &amp; Mobile Commerce</b> , Teaching Assistant	HKU
2023	<b>ELEC3342, Digital system design</b> , Teaching Assistant	HKU
2022	<b>ELEC3342, Digital system design</b> , Teaching Assistant	HKU
2022	<b>ELEC6036, High performance computer architecture</b> , Teaching Assistant	HKU

## Professional Development

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- Reviewer of IEEE Transactions on Circuits and Systems I: Regular Papers (TCAS-I)
- Reviewer of Microelectronics Journal
- Reviewer of IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)